

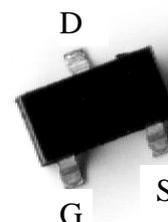
## 20V N-CHANNEL Enhancement Mode MOSFET

### Features:

- Simple drive requirement
- Small package outline
- Capable of 2.5V gate drive
- Pb-free lead plating and halogen-free package

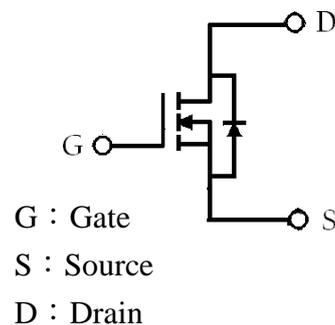
### Outline

SOT-323



### Symbol

KW2302S3



### Ordering Information

Device	Package	Shipping
KW2302S3	SOT-323 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	
Continuous Drain Current @ V <sub>GS</sub> =4.5V, T <sub>A</sub> =25°C (Note 3)	I <sub>D</sub>	2.9	A
Continuous Drain Current @ V <sub>GS</sub> =4.5V, T <sub>A</sub> =70°C (Note 3)		2.3	
Continuous Drain Current @ V <sub>GS</sub> =4.5V, T <sub>A</sub> =25°C (Note 4)		2.3	
Continuous Drain Current @ V <sub>GS</sub> =4.5V, T <sub>A</sub> =70°C (Note 4)		1.8	
Pulsed Drain Current (Notes 1, 2)	I <sub>DM</sub>	30	
Maximum Power Dissipation @ T <sub>A</sub> =25°C	P <sub>D</sub>	0.7 (Note 3)	W
		0.43 (Note 4)	
Operating Junction and Storage Temperature	T <sub>j</sub> , T <sub>stg</sub>	-55~+150	°C

### Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient, max (Note 3)	R <sub>θJA</sub>	178	°C/W
Thermal Resistance, Junction-to-Ambient, max (Note 4)		290	
Thermal Resistance, Junction-to-Case, max	R <sub>θJC</sub>	90	

- Note : 1. Pulse width limited by maximum junction temperature.  
 2. Pulse width ≤ 300μs, duty cycle ≤ 2%.  
 3. Surface mounted on 1 in<sup>2</sup> copper pad of FR-4 board, 2 oz. copper.  
 4. Surface mounted on minimum copper pad, 2 oz. copper.

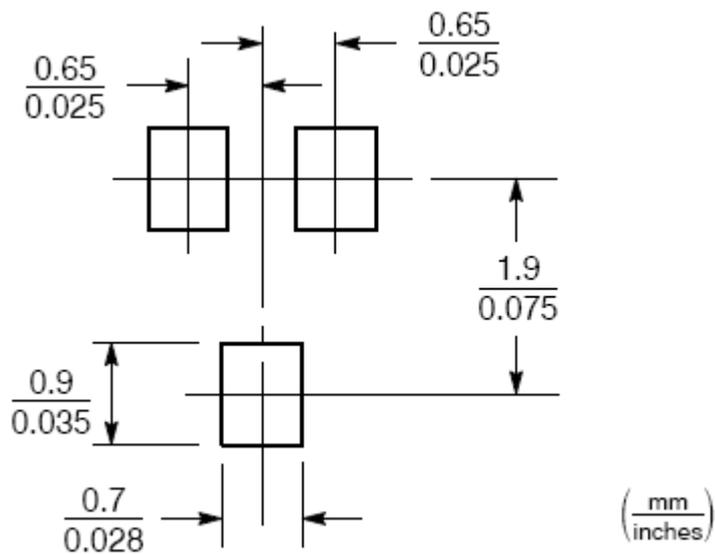
### Electrical Characteristics (T<sub>j</sub>=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	20	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
ΔBV <sub>DSS</sub> /ΔT <sub>j</sub>	-	0.02	-	V/°C	Reference to 25°C, I <sub>D</sub> =250μA
V <sub>GS(th)</sub>	0.5	-	1.2	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V
I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V
	-	-	10		V <sub>DS</sub> =20V, V <sub>GS</sub> =0V (T <sub>j</sub> =70°C)
*R <sub>Ds(ON)</sub>	-	55	66	mΩ	I <sub>D</sub> =2A, V <sub>GS</sub> =4.5V
	-	65	85		I <sub>D</sub> =2A, V <sub>GS</sub> =2.5V
*G <sub>FS</sub>	-	4	-	S	V <sub>DS</sub> =5V, I <sub>D</sub> =2A
<b>Dynamic</b>					
C <sub>iss</sub>	-	440	-	pF	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz
C <sub>oss</sub>	-	61	-		
C <sub>rss</sub>	-	59	-		

$t_{d(ON)}$	-	4.5	-	ns	$V_{DS}=10V, I_D=2A, V_{GS}=5V$ $R_G=6\Omega, R_D=2.8\Omega$
$t_r$	-	7.4	-		
$t_{d(OFF)}$	-	19	-		
$t_f$	-	7.2	-		
$Q_g$	-	4.4	-	nC	$V_{DS}=10V, I_D=2A, V_{GS}=4.5V$
$Q_{gs}$	-	0.7	-		
$Q_{gd}$	-	1.7	-		
<b>Source-Drain Diode</b>					
$*V_{SD}$	-	0.8	1.2	V	$V_{GS}=0V, I_S=1.6A$
$I_S$	-	-	1	A	$V_D=V_G=0V, V_S=1.2V$
$I_{SM}$	-	-	10		

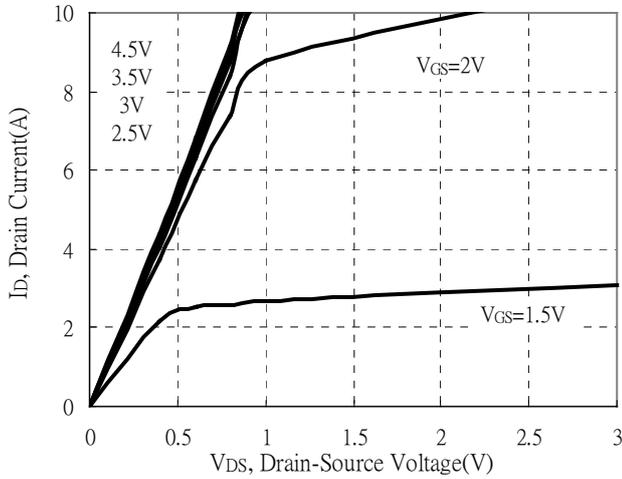
\*Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$

### Recommended Soldering Footprint

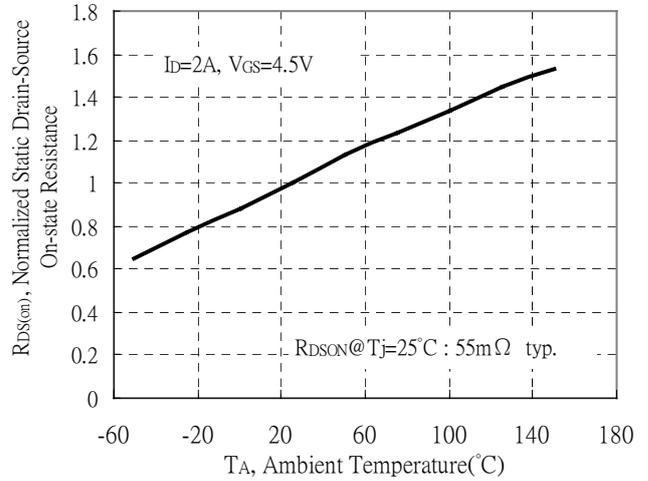


## Typical Characteristics

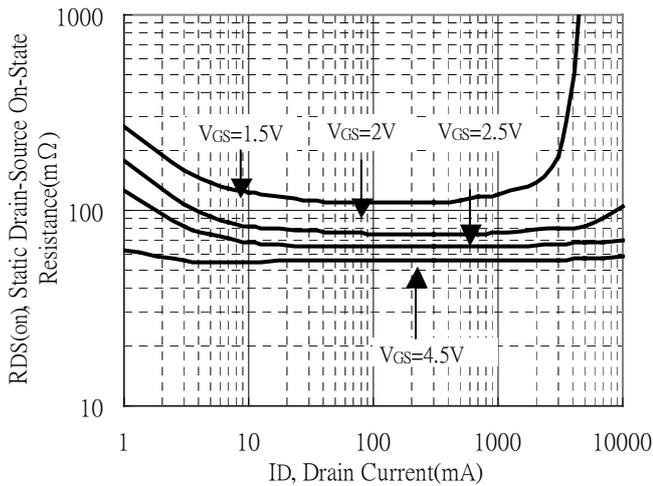
Typical Output Characteristics



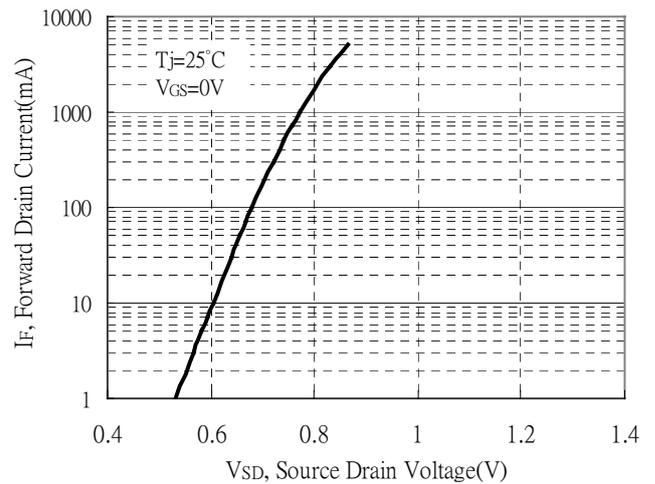
Static Drain-Source On-resistance vs Ambient Temperature



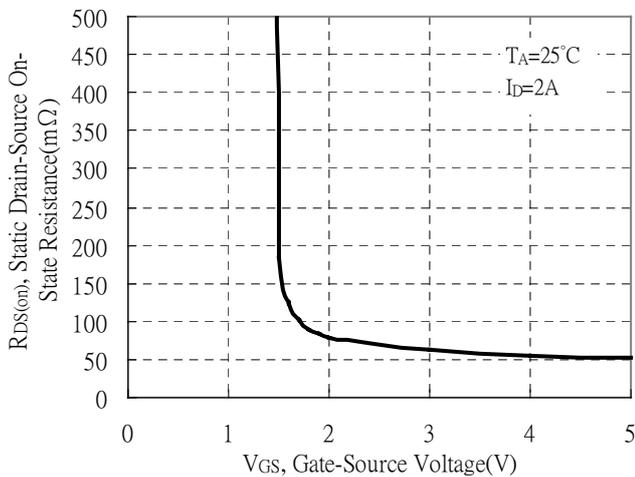
Static Drain-Source On-State resistance vs Drain Current



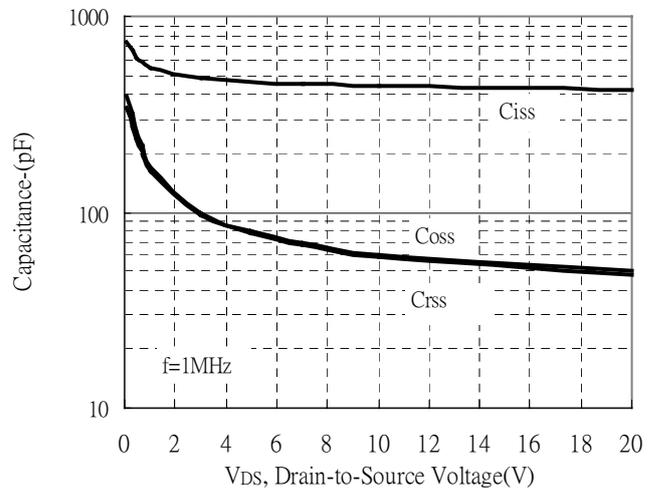
Forward Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

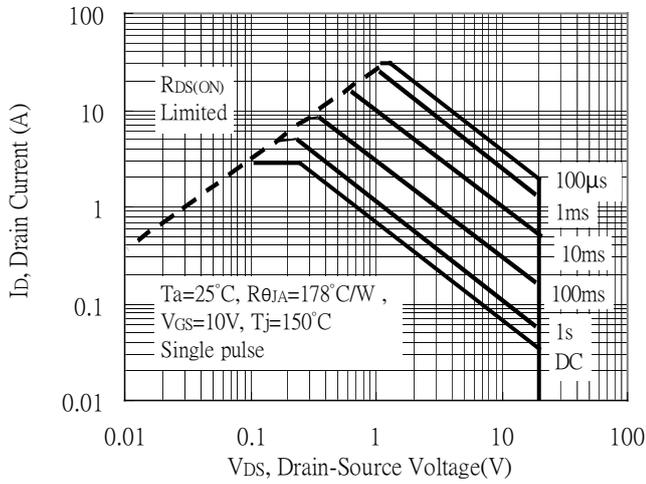


Capacitance vs Reverse Voltage

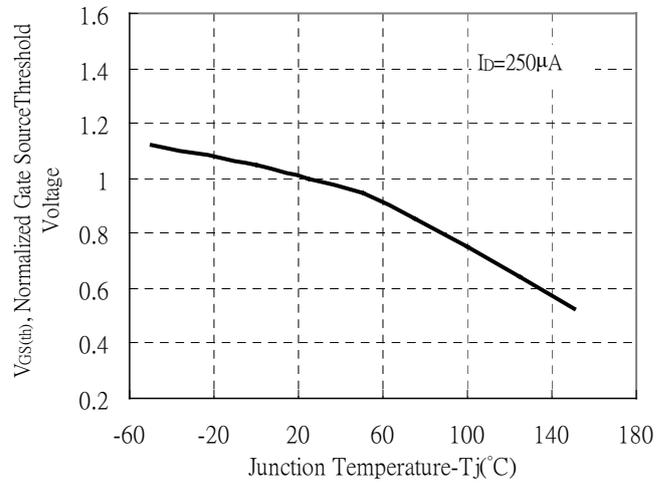


### Typical Characteristics(Cont.)

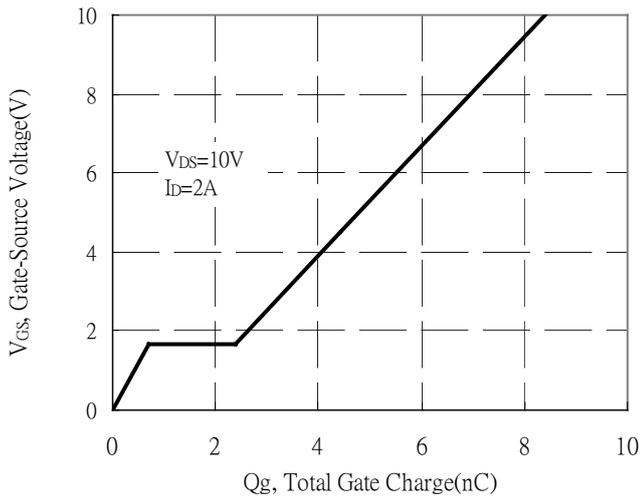
Maximum Safe Operating Area



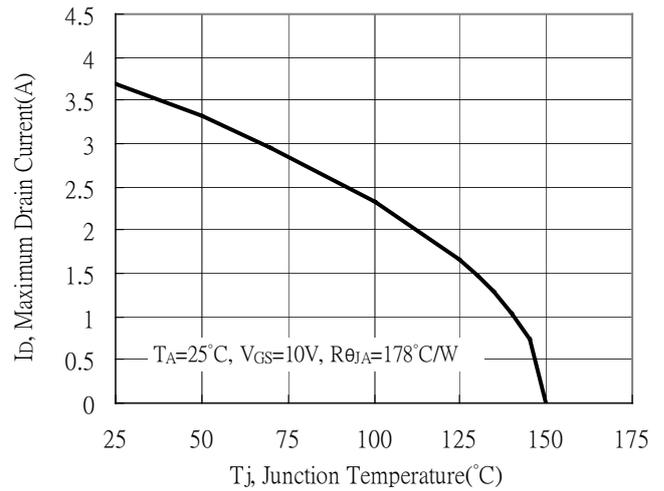
Gate Threshold Voltage vs Ambient Temperature



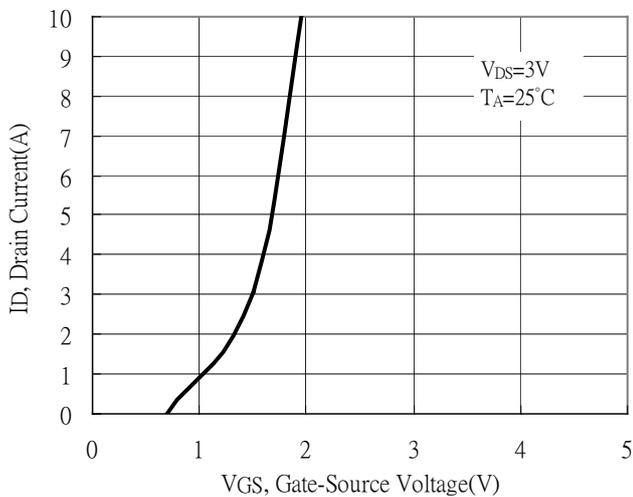
Gate Charge Characteristics



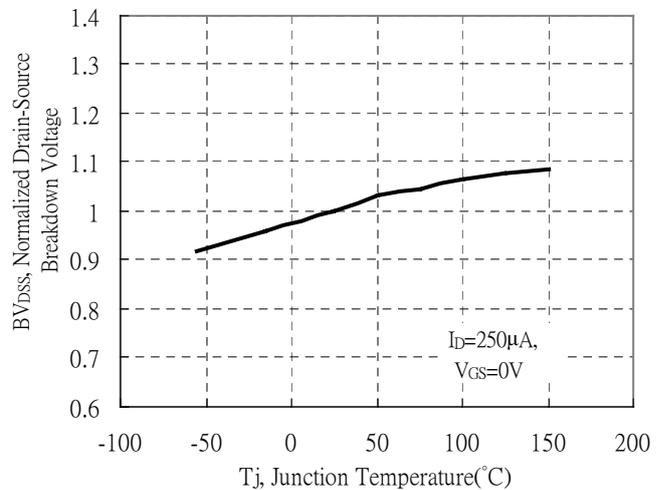
Maximum Drain Current vs Junction Temperature



Drain Current vs Gate-Source Voltage

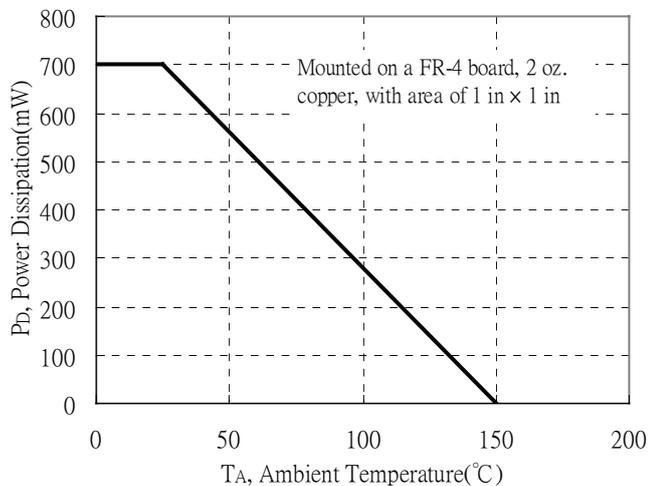


Brekdown Voltage vs Ambient Temperature

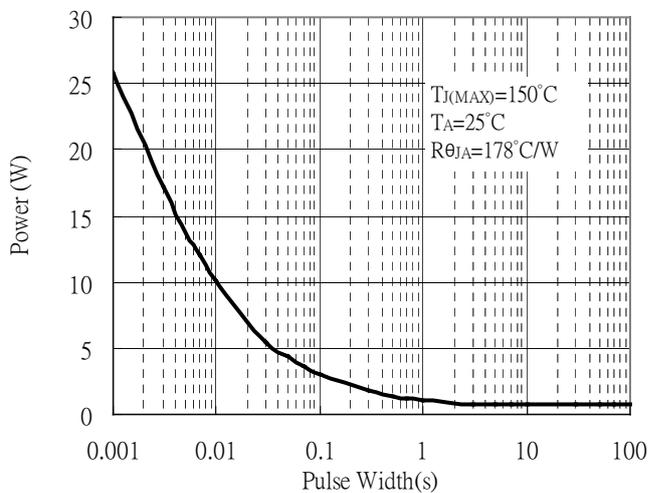


### Typical Characteristics(Cont.)

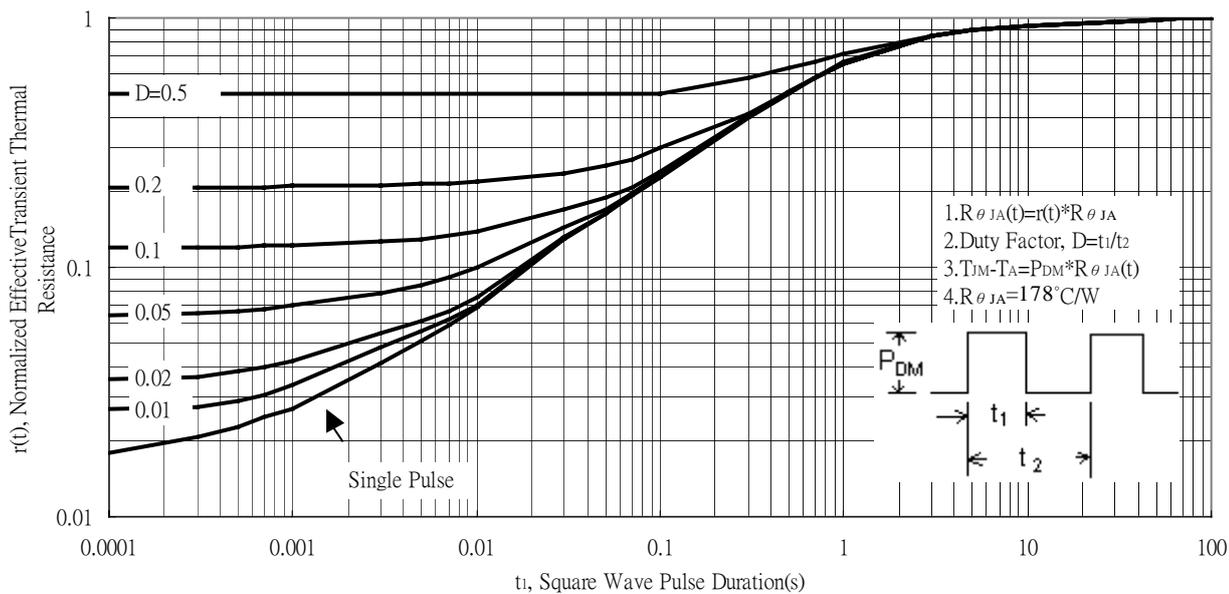
Power Derating Curve



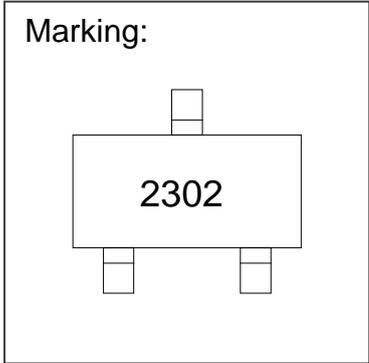
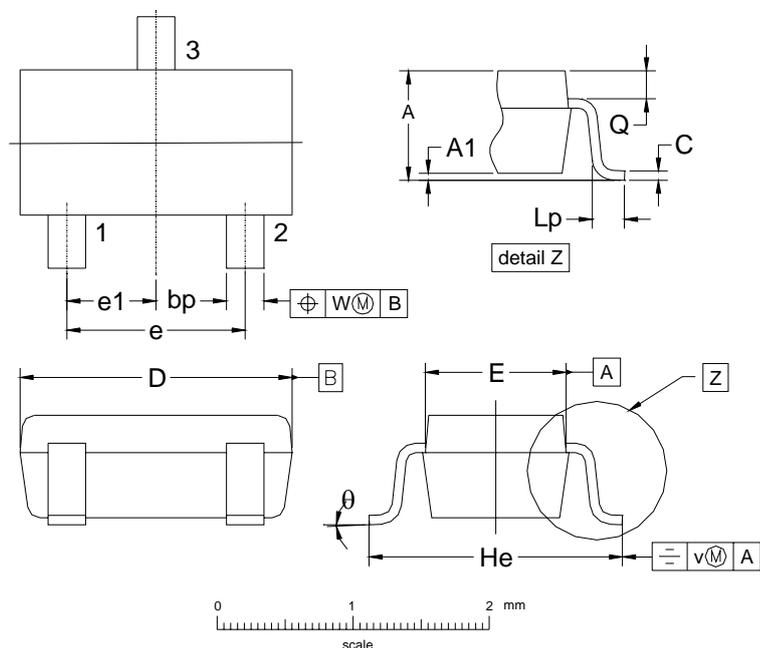
Single Pulse Power Rating, Junction to Ambient



Transient Thermal Response Curves



**SOT-323 Dimension**



3-Lead SOT-323 Plastic Surface Mounted Package  
 Code: S3

Style: Pin 1.Gate 2.Source 3.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0315	0.0433	0.80	1.10	e1	0.0256	-	0.65	-
A1	0.0000	0.0039	0.00	0.10	He	0.0787	0.0886	2.00	2.25
bp	0.0118	0.0157	0.30	0.40	Lp	0.0059	0.0177	0.15	0.45
C	0.0039	0.0098	0.10	0.25	Q	0.0051	0.0091	0.13	0.23
D	0.0709	0.0866	1.80	2.20	v	0.0079	-	0.2	-
E	0.0453	0.0531	1.15	1.35	w	0.0079	-	0.2	-
e	0.0512	-	1.3	-	$\theta$	-	-	10°	0°